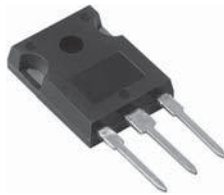
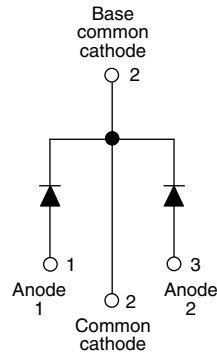


HEXFRED®

Ultrafast Soft Recovery Diode, 2 x 16 A


TO-247AC

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified for industrial level


RoHS
COMPLIANT

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA32PA120CPbF is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 16 A per leg continuous current, the VS-HFA32PA120CPbF is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA32PA120CPbF is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

Package	TO-247AC
$I_{F(AV)}$	2 x 16 A
V_R	1200 V
V_F at I_F	3.0 V
t_{rr} (typ.)	30 ns
T_J max.	150 °C
Diode variation	Single die

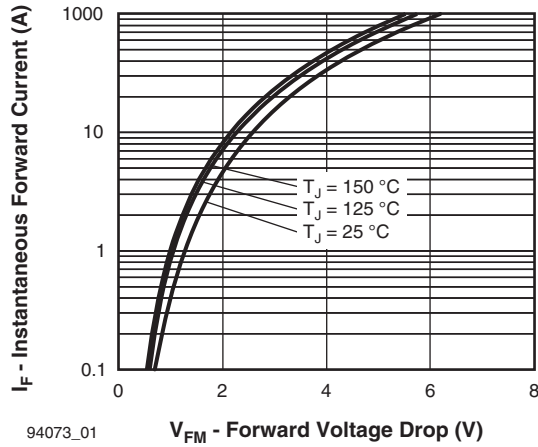
ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	per leg	16
			per device	32
Single pulse forward current	I_{FSM}		190	A
Maximum repetitive forward current	I_{FRM}		64	A
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	151	°C
		$T_C = 100\text{ °C}$	60	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	W

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	1200	-	-	V
Maximum forward voltage	V _{FM}	I _F = 16 A	-	2.5	3.0	
		I _F = 32 A	-	3.2	3.93	
		I _F = 16 A, T _J = 125 °C	-	2.3	2.7	
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	-	0.75	20	μA
		T _J = 125 °C, V _R = 0.8 x V _R rated	-	375	2000	
Junction capacitance	C _T	V _R = 200 V	-	27	40	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

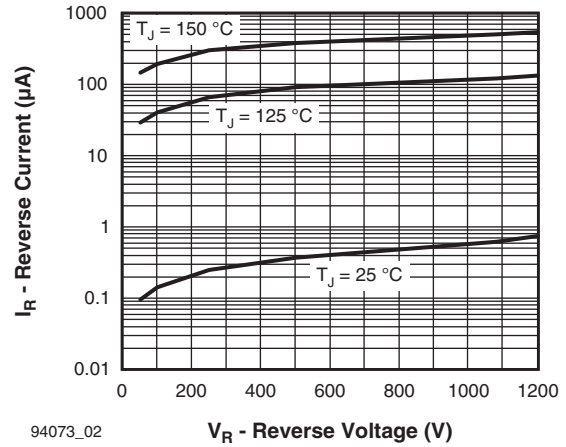
DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 10	t _{rr}	I _F = 1.0 A, di _F /dt = 200 A/μs, V _R = 30 V	-	30	-	ns
	t _{rr1}	T _J = 25 °C	-	90	135	
	t _{rr2}	T _J = 125 °C	-	164	245	
Peak recovery current See fig. 6	I _{RRM1}	T _J = 25 °C	-	5.8	10	A
	I _{RRM2}	T _J = 125 °C	-	8.3	15	
Reverse recovery charge See fig. 7	Q _{rr1}	T _J = 25 °C	-	260	675	nC
	Q _{rr2}	T _J = 125 °C	-	680	1838	
Peak rate of fall of recovery current during t _b See fig. 8	di _{(rec)M} /dt1	T _J = 25 °C	-	120	-	A/μs
	di _{(rec)M} /dt2	T _J = 125 °C	-	76	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	0.83	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.50	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC (JEDEC)	HFA32PA120C			



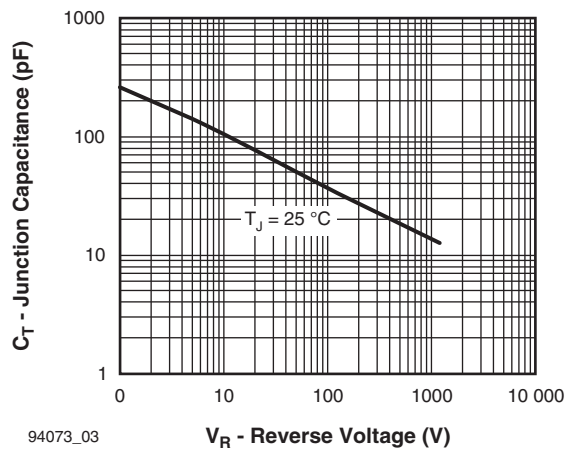
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Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current



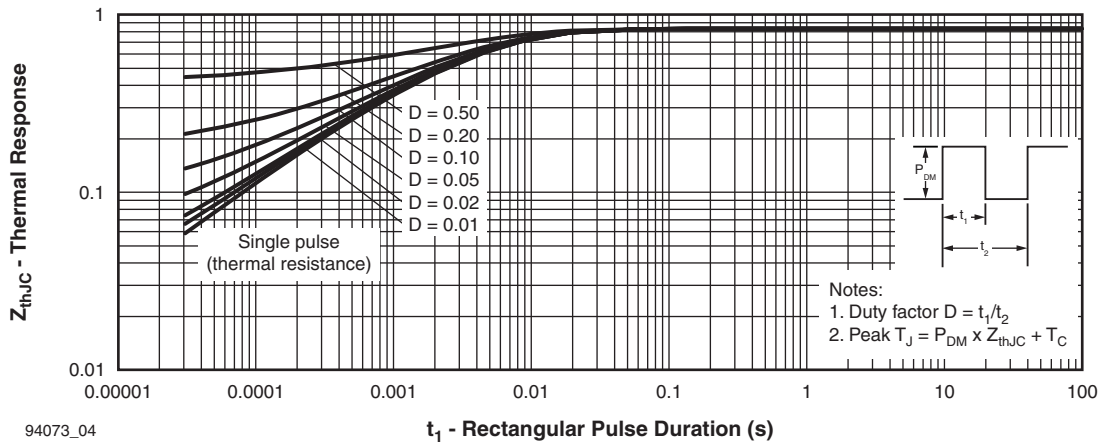
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Fig. 2 - Typical Reverse Current vs. Reverse Voltage



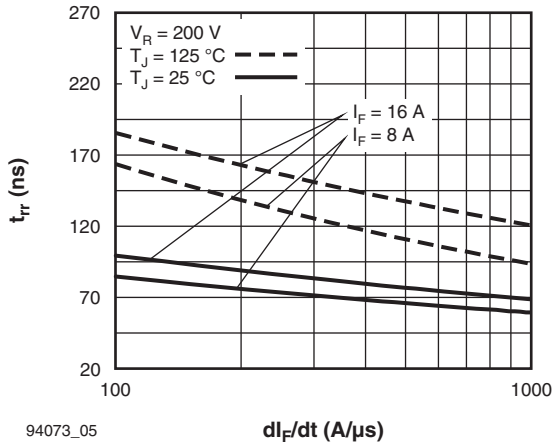
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Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage



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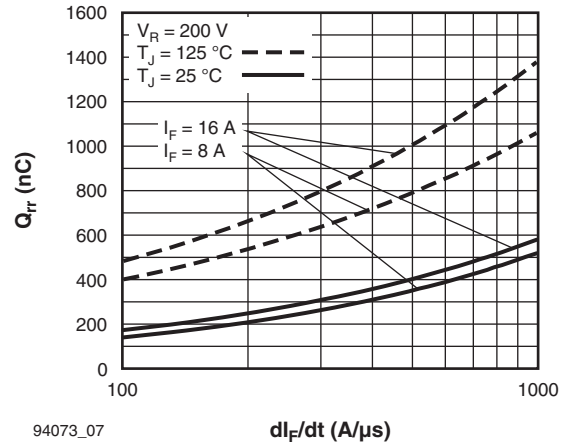
Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



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di_F/dt (A/ μ s)

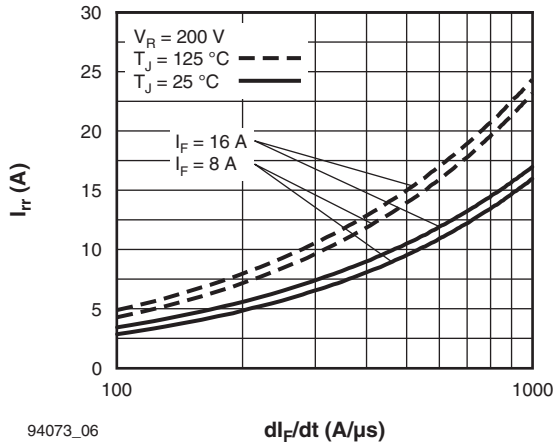
Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt (Per Leg)



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di_F/dt (A/ μ s)

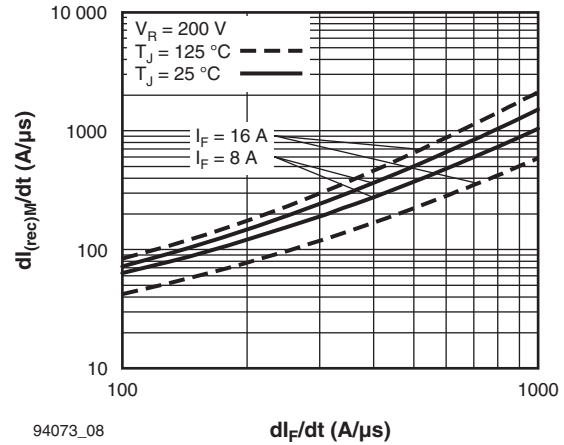
Fig. 7 - Typical Stored Charge vs. di_F/dt (Per Leg)



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di_F/dt (A/ μ s)

Fig. 6 - Typical Recovery Current vs. di_F/dt (Per Leg)



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di_F/dt (A/ μ s)

Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt (Per Leg)

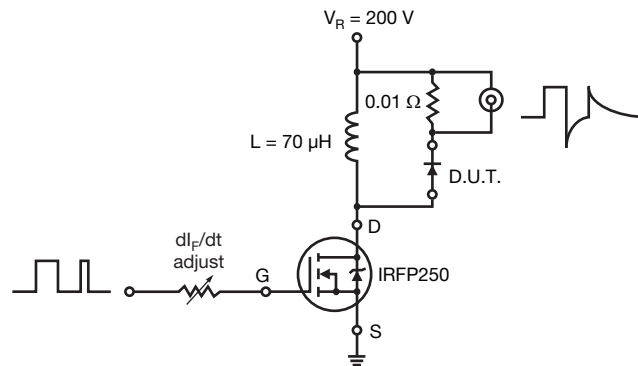


Fig. 9 - Reverse Recovery Parameter Test Circuit

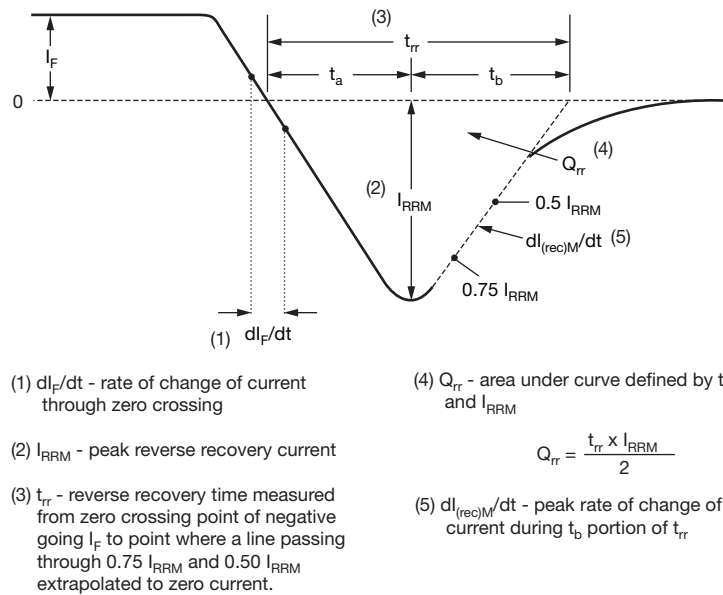


Fig. 10 - Reverse Recovery Waveform and Definitions

VS-HFA32PA120CPbF



Vishay Semiconductors

HEXFRED®
Ultrafast Soft Recovery Diode, 2 x 16 A

ORDERING INFORMATION TABLE

Device code	VS-	HF	A	32	PA	120	C	PbF
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (32 = 32 A)
- 5** - PA = TO-247AC
- 6** - Voltage rating: (120 = 1200 V)
- 7** - Circuit configuration
C = Common cathode
- 8** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95223
Part marking information	www.vishay.com/doc?95226



DIMENSIONS in millimeters and inches



Lead assignments

- Diodes**
 1. - Anode/open
 2. - Cathode
 3. - Anode

SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		D2	0.51	1.30	0.020	0.051	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.50	2.49	0.059	0.098		E1	13.72	-	0.540	-	
b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
b1	0.99	1.35	0.039	0.053		FK	2.54		0.010		
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.37	0.065	0.094		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		N	7.62 BSC		0.3		
b5	2.59	3.38	0.102	0.133		ΦP	3.56	3.66	0.14	0.144	
c	0.38	0.86	0.015	0.034		ΦP1	-	6.98	-	0.275	
c1	0.38	0.76	0.015	0.030		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	1.78	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC		0.217 BSC		

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Contour of slot optional
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Thermal pad contour optional with dimensions D1 and E1
- Lead finish uncontrolled in L1
- Φ P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- Outline conforms to JEDEC outline TO-247 with exception of dimension c



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